

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology
- ★ 100% EAS Guaranteed

Product Summary

RoHS

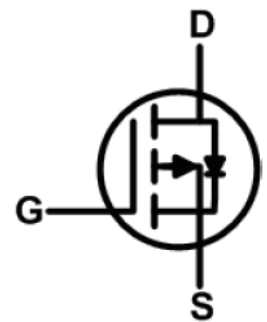
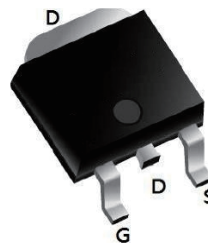
| BVDSS | RDS(ON) | ID |
|-------|---------|------|
| -100V | 180mΩ | -10A |

Description

The 10P10 is the high cell density trenched N-ch MOSFETs, which provide excellent RDS(ON) and gate charge for most of the synchronous buck converter applications.

The 10P10 meet the RoHS and Green Product, requirement 100% EAS guaranteed with full function reliability approved.

TO252 Pin Configuration



Absolute Maximum Ratings

| Symbol | Parameter | Rating | Unit |
|---------------------------------------|---|------------|------|
| V _{DS} | Drain-Source Voltage | -100 | V |
| V _{GS} | Gate-Source Voltage | ±20 | V |
| I _D @T _C =25°C | Continuous Drain Current, V _{GS} @ -10V ¹ | -10 | A |
| I _D @T _C =100°C | Continuous Drain Current, V _{GS} @ -10V ¹ | -4 | A |
| I _D @T _A =25°C | Continuous Drain Current, V _{GS} @ -10V ¹ | -2.5 | A |
| I _D @T _A =70°C | Continuous Drain Current, V _{GS} @ -10V ¹ | -2 | A |
| I _{DM} | Pulsed Drain Current ² | -20 | A |
| EAS | Single Pulse Avalanche Energy ³ | 48.1 | mJ |
| I _{AS} | Avalanche Current | -14 | A |
| P _D @T _C =25°C | Total Power Dissipation ⁴ | 10 | W |
| P _D @T _A =25°C | Total Power Dissipation ⁴ | 2 | W |
| T _{STG} | Storage Temperature Range | -55 to 150 | °C |
| T _J | Operating Junction Temperature Range | -55 to 150 | °C |

Thermal Data

| Symbol | Parameter | Typ. | Max. | Units |
|------------------|--|------|------|-------|
| R _{θJA} | Thermal Resistance Junction-Ambient ¹ | --- | 72 | °C/W |
| R _{θJC} | Thermal Resistance Junction-Case ¹ | --- | 8 | °C/W |

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

| Symbol | Parameter | Test condition | Min. | Typ. | Max. | Units |
|--------------|--|--|------|------|-----------|------------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS}=0V, I_D=-250\mu A$ | -100 | --- | --- | V |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance ² | $V_{GS}=-10V, I_D=-3A$ | --- | 180 | 220 | m Ω |
| | | $V_{GS}=-4.5V, I_D=-2A$ | --- | 210 | 255 | m Ω |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{GS}=V_{DS}, I_D=-250\mu A$ | -1.2 | --- | -2.5 | V |
| I_{DSS} | Drain-Source Leakage Current | $V_{DS}=-80V, V_{GS}=0V, T_J=25^\circ\text{C}$ | --- | --- | -1 | μA |
| | | $V_{DS}=-80V, V_{GS}=0V, T_J=85^\circ\text{C}$ | --- | --- | -30 | μA |
| I_{GSS} | Gate-Source Leakage Current | $V_{GS}=\pm 20V, V_{DS}=0V$ | --- | --- | ± 100 | nA |
| R_g | Gate Resistance | $V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$ | --- | 13 | --- | Ω |
| Q_g | Total Gate Charge (-10V) | $V_{DS}=-50V, V_{GS}=-10V, I_D=-2A$ | --- | 19 | --- | nC |
| Q_{gs} | Gate-Source Charge | | --- | 3.4 | --- | nC |
| Q_{gd} | Gate-Drain Charge | | --- | 2.9 | --- | nC |
| $T_{d(on)}$ | Turn-On Delay Time | $V_{DD}=-30V, V_{GS}=-10V, R_G=3.3\Omega, I_D=-1A$ | --- | 9 | --- | ns |
| T_r | Rise Time | | --- | 6 | --- | |
| $T_{d(off)}$ | Turn-Off Delay Time | | --- | 39 | --- | |
| T_f | Fall Time | | --- | 33 | --- | |
| C_{iss} | Input Capacitance | $V_{DS}=-30V, V_{GS}=0V, f=1\text{MHz}$ | --- | 1228 | --- | pF |
| C_{oss} | Output Capacitance | | --- | 41 | --- | pF |
| C_{rss} | Reverse Transfer Capacitance | | --- | 29 | --- | pF |

Diode Characteristics

| Symbol | Parameter | Test condition | Min. | Typ. | Max. | Units |
|----------|--|--|------|------|------|-------|
| I_S | Continuous Source Current ^{1,5} | $V_G=V_D=0V$, Force Current | --- | --- | -10 | A |
| V_{SD} | Diode Forward Voltage ² | $V_{GS}=0V, I_S=-1A, T_J=25^\circ\text{C}$ | --- | --- | -1.2 | V |

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
2. The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. The EAS data shows Max. rating. The test condition is $V_{DD}=-25V, V_{GS}=-10V, L=0.1\text{mH}, I_{AS}=-14A$
4. The power dissipation is limited by 150°C junction temperature
5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

P-Channel Typical Characteristics

Figure 1: Output Characteristics

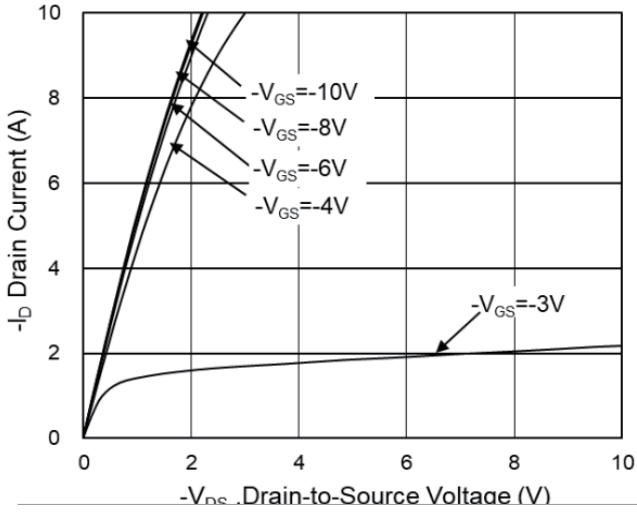


Figure 2: On-Resistance vs. G-S Voltage

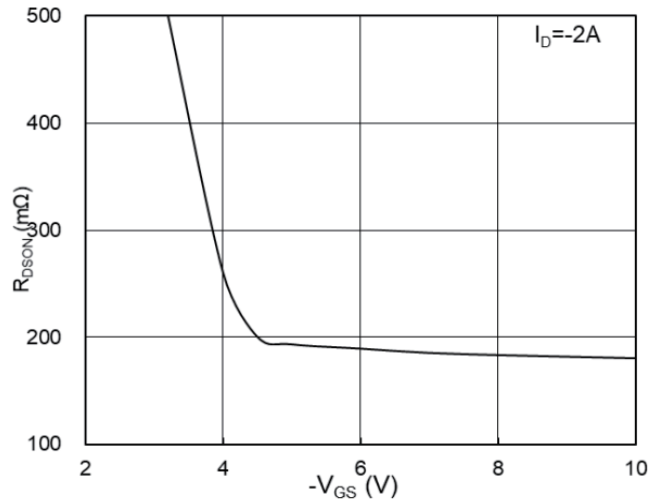


Figure 3: Forward Characteristics Of Reverse

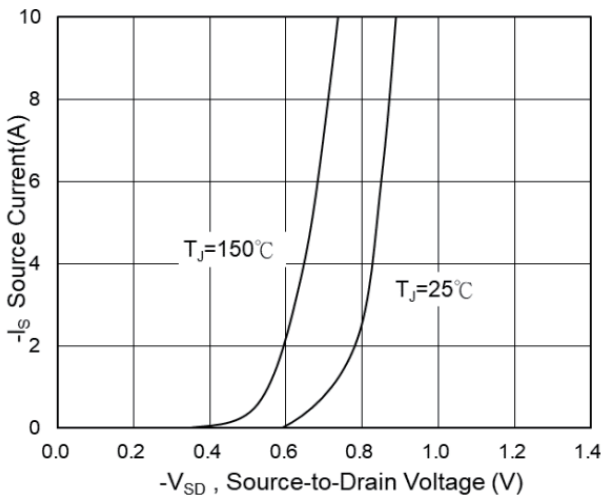


Figure 4: Gate-Charge Characteristics

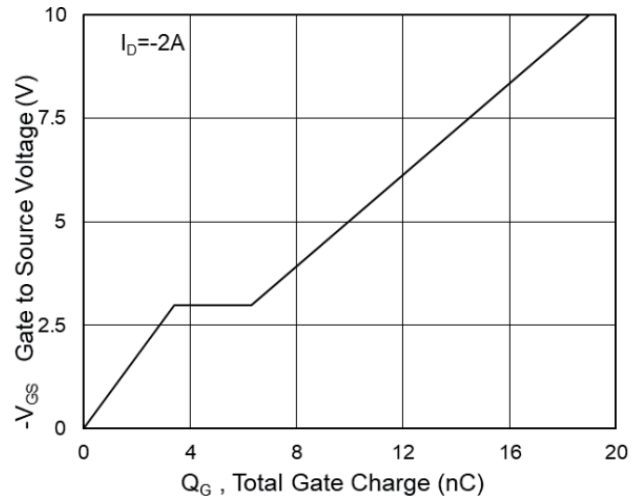


Figure 5: Normalized VGS(th) vs. TJ

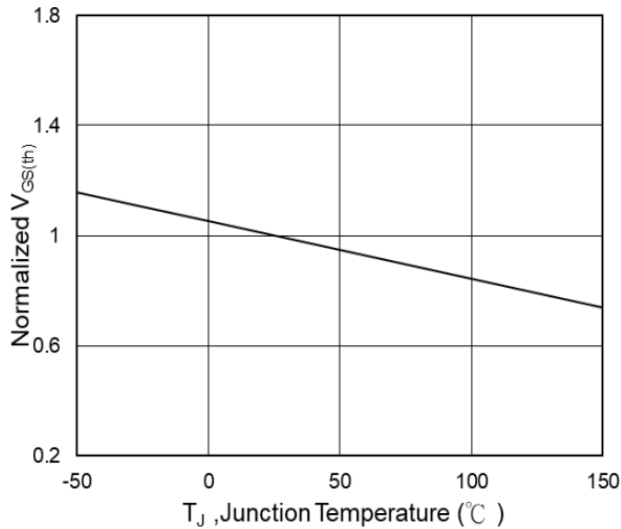
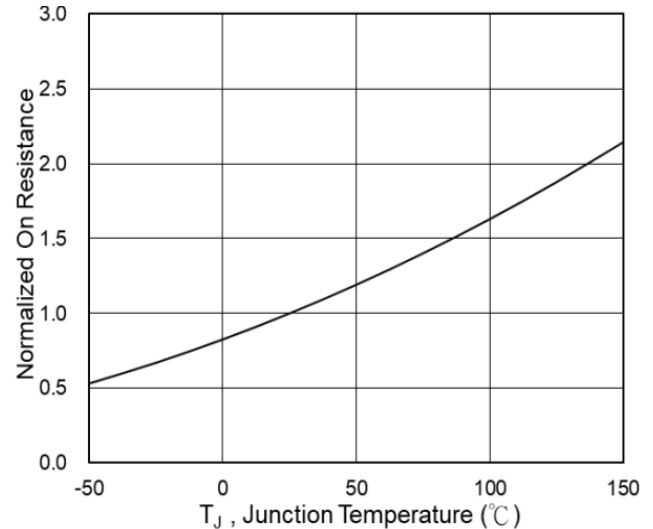


Figure 6: Normalized RDS(on) vs. TJ



Typical Performance Characteristics

Figure 7: Capacitance

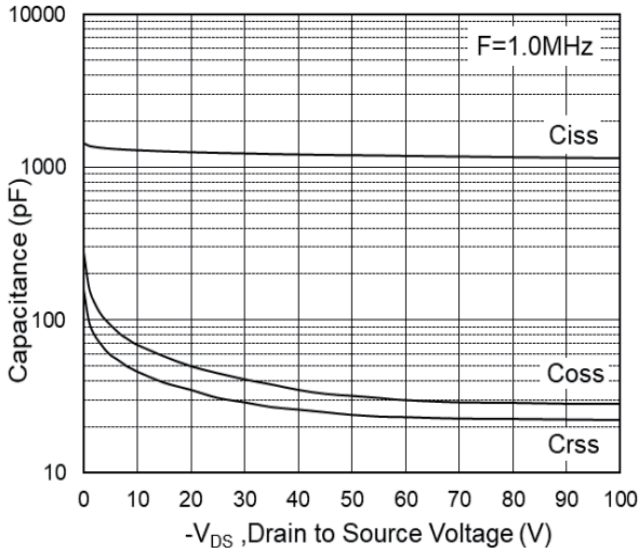


Figure 8: Safe Operating Area

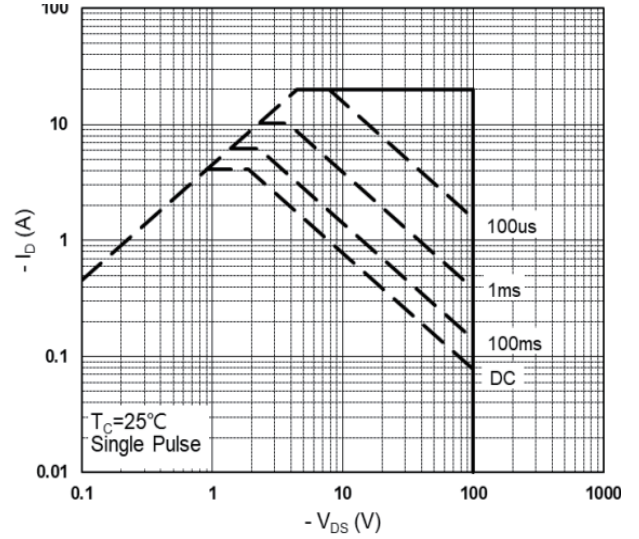


Figure 9: Normalized Maximum Transient Thermal Impedance

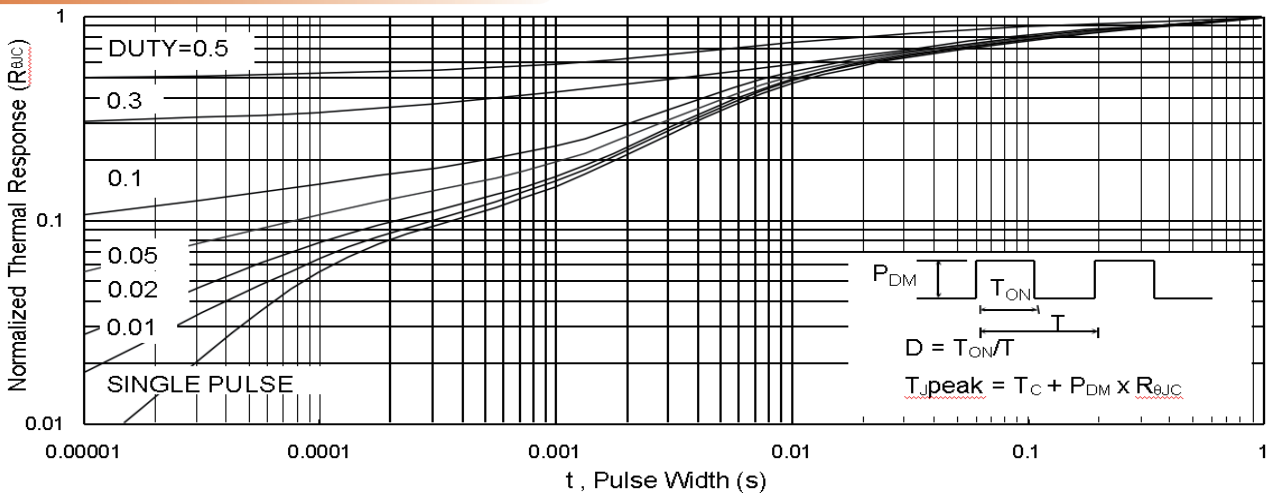


Figure 10: Switching Time Waveform

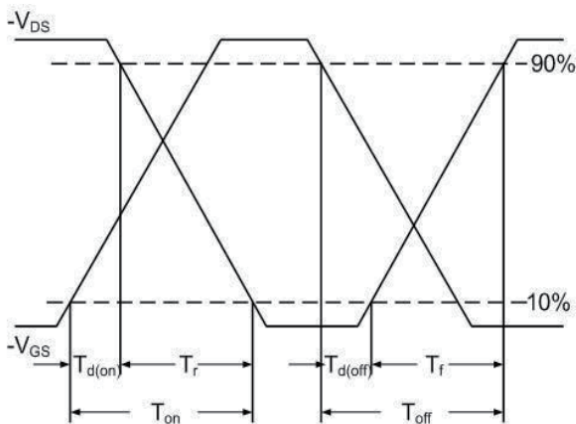
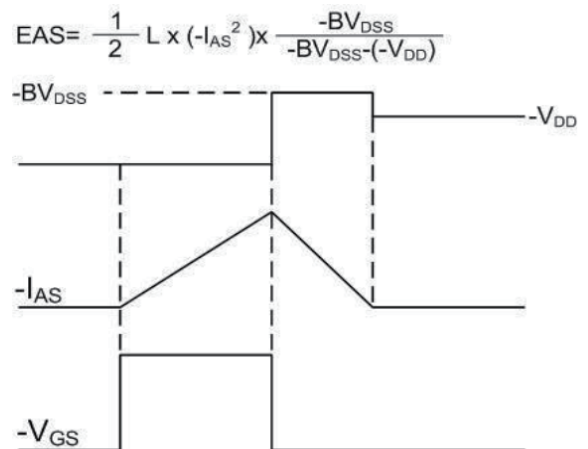
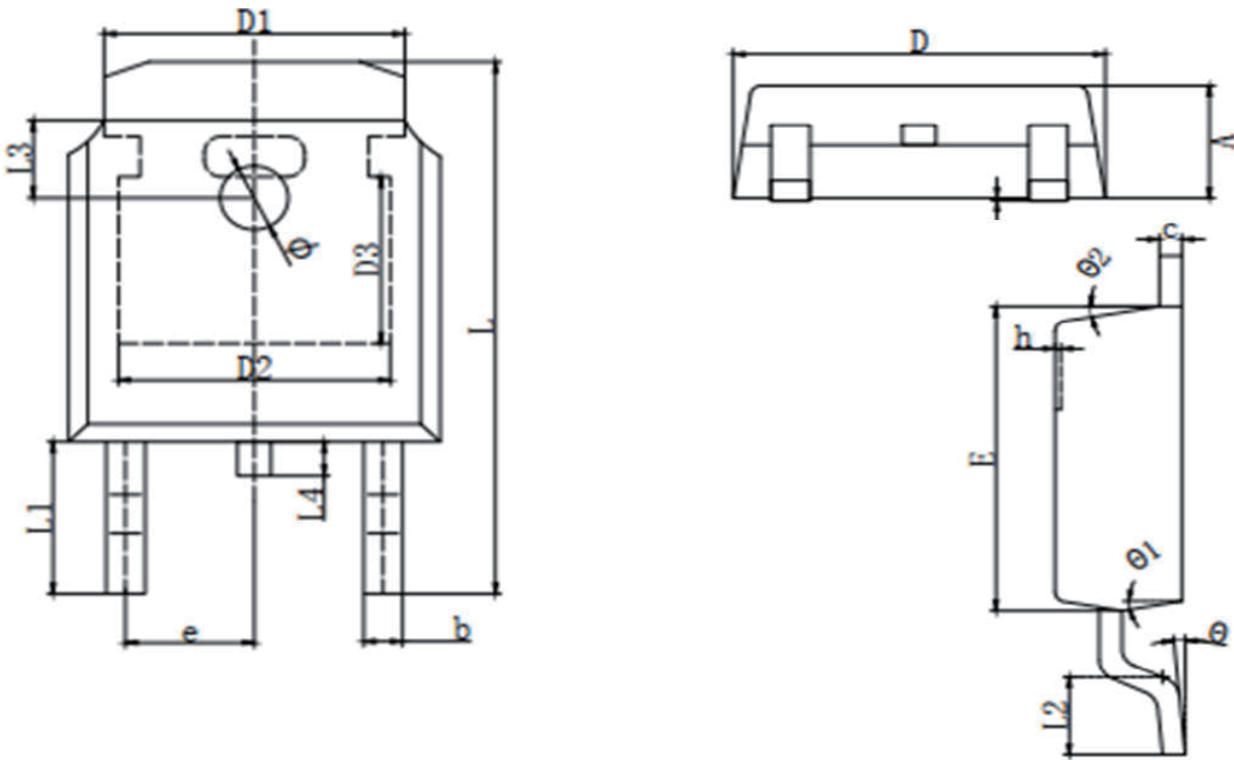


Figure 11: Unclamped Inductive Switching



TO-252 Package outline



| Symbol | MILLMETER | | Symbol | MILLMETER | |
|--------|-----------|-------|----------------|-----------|-------|
| | MIN | MAX | | MIN | MAX |
| A | 2.200 | 2.400 | h | 0.000 | 0.200 |
| A1 | 0.000 | 0.127 | L | 9.900 | 10.30 |
| b | 0.640 | 0.740 | L1 | 2.888REF | |
| c | 0.460 | 0.580 | L2 | 1.400 | 1.700 |
| D | 6.500 | 6.700 | L3 | 1.600REF | |
| D1 | 5.334REF | | L4 | 0.600 | 1.000 |
| D2 | 4.826REF | | ∅ | 1.100 | 1.300 |
| D3 | 3.166REF | | θ | 0° | 8° |
| E | 6.00 | 6.200 | θ ₁ | 9° TYP2 | |
| e | 2.286TYP | | θ ₂ | 9° TYP | |